

GSCP Intern at San Disk – Milipitas

Analysis of Sample Supply chain Dataset provided by Tony on Interview reference

Dataset Contents

– Bill of Materials

- **BOMID**
- **Product ID**
- **Component ID**

– Forecast Actuals

- **Product ID**
- **Week**
- **Forecasted Demand**
- **Actual Demand**

– On-hand Inventory

- **Component ID**
- **On Hand Inventory**

– Product Information

- **Product ID**
- **ProductName**
- **Category**
- **Sales Price (\$)**

– Supplier and Component Details

- **Component ID**
- **Supplier ID**
- **Lead Time (Days)**
- **Cost (\$)**

1. Excel Analysis (Supplier Sample data – SD)

- **Forecast Accuracy** → Demand Planning
→ Calculated error and accuracy % per product using Pivot Tables and visualized underperforming forecasts.
- **Inventory Risk** → Inventory Optimization
→ Exploded product forecasts to component-level demand using the BOM, then compared with on-hand inventory to flag stockout risks.
- **Supplier Risk** → Supply Chain Resilience
→ Identified components with single suppliers and long lead times using COUNTIF and AVERAGEIF — key for supply continuity.
- **Build Cost** → Supply Chain Resilience
→ Used MINIFS to select lowest-cost suppliers, summed total build cost per product, and compared against sales price to assess profitability.

2. Power BI Dashboard Analysis (Supplier Sample data – SD)

- **Forecast Accuracy Overview** - *Analyzes how accurately demand was forecasted per product.*
 - Visualizes **Avg Forecast Accuracy %**
 - Highlights products with **high forecast error**
 - KPI card shows **overall forecasting performance**
- **Inventory Risk Analysis** - *Evaluates component-level inventory vs demand to spot shortages.*
 - Compares **Total Component Demand** vs **On-Hand Inventory**
 - Flags **Inventory Gaps** (shortages)
 - KPI shows **# of components at risk of stockout**
- **Supplier Risk Summary** - *Assesses supply continuity risk based on lead times and supplier count.*
 - Shows **Avg Lead Time per component**
 - Donut chart splits **Single vs Multiple Suppliers**
 - Highlights components that are **dependent on only one supplier**
- **Build Cost & Profitability** - *Analyzes cost to build each product and compares it with sales price.*
 - Charts **Build Cost vs Sales Price**
 - Calculations **Profit per product**, KPI shows **Total Profit or Avg Profit Margin**

3.Data-Driven Supply Chain Optimization: Demand Forecasting, Shortage Prediction, and Supplier Risk Evaluation Using ML – Python/Collab

- **Forecast Accuracy Summary (Top 5 Products)**

| Product ID | Forecasted Demand | Actual Demand | Forecast Error | Forecast Accuracy (%) |
|------------|-------------------|---------------|----------------|-----------------------|
| 12 | 1547 | 1979 | 43.69 | 97.79% |
| 13 | 1852 | 1822 | 40.77 | 97.76% |
| 8 | 1809 | 1845 | 45.38 | 97.54% |
| 5 | 1800 | 1807 | 45.15 | 97.50% |
| 19 | 1455 | 1917 | 48.77 | 97.46% |

- **Product Risk Summary (Top 5 by Shortage Risk or Low Inventory)**

| Product ID | Forecasted Demand | On-Hand Inventory | Build Cost | Profit Per Unit | Shortage Risk |
|------------|-------------------|-------------------|------------|-----------------|---------------|
| 10 | 1544 | 4054 | \$39.00 | -\$18.40 | 1 |
| 14 | 1322 | 4504 | \$101.33 | -\$5.33 | 1 |
| 8 | 1809 | 5519 | \$50.17 | -\$10.47 | 0 |
| 6 | 1809 | 5643 | \$73.33 | -\$48.93 | 0 |
| 5 | 1800 | 5861 | \$31.67 | -\$6.67 | 0 |

- **Supplier Risk Summary (Top 5 High-Risk Components)**

| Component ID | Number of Suppliers | Average Lead Time (days) | Average Cost | Risk Level |
|--------------|---------------------|--------------------------|--------------|------------|
| 7 | 1 | 14.0 | \$6.00 | High |
| 24 | 1 | 14.0 | \$7.00 | High |
| 5 | 1 | 12.5 | \$7.00 | High |
| 16 | 1 | 7.0 | \$11.00 | Low/Medium |
| 4 | 1 | 6.0 | \$15.00 | Low/Medium |

Final Summary

| Area | Key Takeaway |
|---------------------|--|
| Forecast Accuracy | Excellent (>97%) forecasts highly reliable |
| Product Risk | Inventory healthy, but profit per unit is negative |
| Supplier Risk | 3 components are single source with long lead time |
| Profit Prediction | Model captures loss trend, but has high error — needs tuning |
| Shortage Prediction | Model detects no-risk cases well, but misses real shortages |

Tools Used:

- **Python in Google Colab**
- **Pandas, NumPy** – data handling
- **Matplotlib, Seaborn** – data visualization
- **Scikit-learn** – ML models and evaluation
- **XGBoost** – advanced regression model
- **Pipeline + ColumnTransformer** – for preprocessing and modeling

ML Methods Used:

| Purpose | Method | Explanation |
|--------------------------|--|---|
| Demand Forecasting | Linear Regression (Sklearn), XGBoost | Predict actual demand using weekly & forecasted demand as inputs, For more accuracy |
| Feature Handling | OneHotEncoding | Converted Product IDs into numeric format |
| Model Evaluation | Mean Squared Error, R² Score | To assess model performance |
| Shortage Risk Prediction | Binary label creation | Compared total inventory vs demand forecast to flag shortage |
| Visualization | Plotting actual vs predicted demand | To show prediction accuracy and trend alignment |

INPUTS for Project Proposal at San disk

1.My projects and Coursework related to San disk

Courses:

ISE 140: Operations Planning and Control

ISE 167: System Simulation

ISE 250: Leading the Six Sigma Improvement Project

ISE 230: Advanced Operations Research

ISE 235: Quality Assurance and Reliability

ISE 251: Managing the Lean Enterprise Improvement Program

ISE 245: Advanced Supply Chain Engineering

ISE 247: Logistics for Supply Chain – Ongoing currently

ISE 240: Analytics for Systems Engineering- Ongoing currently

ISE 244: AI Tools and Practice for Systems Engineering- Ongoing currently

Projects:

ISE 140: Operations Planning and Control – Dr Anil Kumar

- Used **Time Series-Exponential smoothing, FIT** model for demand forecasting with MAD validation.
- Developed **MRP** and **capacity plans** from BOM and production data.
- Built cost-efficient production schedules using level & chase strategies.
- Applied Pro-Model for simulation-based scheduling to minimize makespan.
- Focused on **forecasting, inventory control, and cycle time reduction** – directly relevant to SanDisk GSCP tasks.

ISE 167 – System Simulation – Dr Khaled Mbrouk

- Simulated **factory floor operations** to optimize **workforce and machine utilization**.
- Improved **throughput** and reduced bottlenecks using discrete-event simulation.
- Relevant to SanDisk for **capacity planning** and **digital twin applications**.

ISE 250 – Leading the Six Sigma Improvement Project -Dr Jacob Tsao – (Green belt)

- Applied **Six Sigma tools** (SPC, MSA, DMAIC) in a **manufacturing environment**.
- Used **Minitab** for statistical analysis and **process optimization**.
- Aligns with SanDisk goals in **quality improvement** and **data-driven decision making**.

ISE 251 – Managing the Lean Enterprise Improvement Program (GWAR)

- Used **AHP, TOPSIS, and VSM** to evaluate and optimize **supplier selection strategies**.

ISE 230 – Advanced Operations Research

- Built and solved **LP/IP models** for optimizing logistics networks and inventory allocation.
- Applied **queuing theory, Little's Law, and Markov chains** for demand and throughput analysis, with robust model validation.

Understanding San Disk

2. Manufacturing Process at SD-Kioxia

flash → built using floating gate transistors.
MP

1. Wafer fabrication [Front-End Manuf.]

Billion Wafer [Creating billions of memory cells on chip]. In GMB 150 class & fab.

Process

- ↳ Photolithography - prints circuit patterns using light
- ↳ Etching - remove material layering for pattern creation
- ↳ Deposition - lay down insulating & conductive layers

Data

- ↳ Tool Utilization [machine bottlenecks]
- ↳ yield rates → % of functional dies per wafer
- ↳ Process time → time taken by each layer
- ↳ WIP inventory → how many are stuck in mid process.

SC Analytics

- Cycle time Analysis → Predict delays / downtime
- Yield forecasting → Link defects to process variables in
- Capacity planning → Optimize machine schedule & Shifts.

2. Wafer testing & sorting

Each die/chip is tested for functionality

Data

P/F results for each die

Bin Sorting → categorized for H/F

Defect mapping - Spatial mapping of failures on Wafer

SC An

- ↳ Defect trend prediction - Identify Hot Spot Over time by Oper.
- ↳ Cycle yield Optimizer - help forecast which margin can have high margin market.

3. Assembly & packaging [Back-End Manufacturing]

dies are bonded to packages, encapsulate to final chip form

Data → Die Attach yield

Package-level test data

Lead time per Assembly line

Supp. Data -

SC A

Supplies performance monitoring

Process line balances

Scrap/rework analysis where/why material got rejected

4. Final testing

Performance / Speed test tests

Data

Throughput per testing Equipment

SC

Preventive maintenance - On test eqp to reduce downtime

Quality trend tracking

→ Avoid product line or facilities

5. Product integration

chip with PCB/controller & SSD, USB, card.

Data Component

- ↳ BOMs
- ↳ LT for PCB, controller
- ↳ Assembly time & defect rate.

SC Data

Inventory Optimization - Align fresh supply with customer availability

*** [EQD] order - Predict slow moving SKUs.

Product led DP - B to S v/s B to O. Stock keeping unit

[Logistics]

6. Packaging, Distribution & Delivery

Data

- Order fulfillment rates
- Warehouse inventory levels
- Shipping lead times
- Customer demand forecasts

SCD

- Forecasting - Historic Sales + Ext data
- Logistic Optimization - Minimizing Shipping Cost vs Delivery Speed
- Carbon foot print analysis
- For Sustainability Insights ESD Highlighted States

SanDisk Manufacturing Process

1. Wafer Fabrication (Front-End)

- Silicon wafers used to create memory cells using floating gate transistors.
- Processes include photolithography, etching, and deposition for layer creation.

2. Wafer Testing & Sorting

- Each die is tested for functionality (P/F results), then sorted (e.g., HP/LG).
- Defect mapping and spatial failure analysis support yield tracking.

3. Assembly & Packaging (Back-End)

- Dies are bonded to packages to form final chips.
- Data includes die attach yield, package hit rate, and assembly lead time.

4. Final Testing

- Performance/speed testing per device.
- Data collected: throughput per equipment.

5. Product Integration

- Assembled with PCB/controllers to form SSDs, USBs, etc.
- BOMs, assembly time, and defect rates tracked.
- Absolutely! Here's the table in plain text format, easy to copy into Word:

Supply Chain Data and KPIs by Manufacturing Process Step

| Manufacturing Step | Relevant SC Data / KPIs |
|----------------------------|--|
| 1. Wafer Fabrication | Tool utilization, machine bottlenecks, yield rate (functional dies per wafer), process time, WIP inventory |
| 2. Wafer Testing & Sorting | P/F results, bin sorting, defect mapping (spatial), defect trend prediction, yield forecasting |
| 3. Assembly & Packaging | Die attach yield, package hit rate, lead time, supplier data, scrap/root cause analysis |
| 4. Final Testing | Throughput per test equipment, speed and performance metrics |
| 5. Product Integration | BOMs, lead time for PCB/controllers, assembly time, defect rate, E&O reduction, slow-moving SKU tracking |

MP-SC perspective - Key KPIs

| Stage | KPIs | Use in SCP Methodology |
|---------------------------------------|---|--|
| Demand Forecasting | Forecast Accuracy (MAPE, WAPE), Service Level | Time series forecasting, planning alignment |
| Wafer Fabrication | Tool Utilization, WIP Inventory, Fab Yield % | Capacity optimization, bottleneck analysis |
| Wafer Testing | Bin Yield %, Scrap Rate, Test Throughput | Product mix planning, predictive quality analysis |
| Assembly & Packaging | Assembly Lead Time, First Pass Yield, Defect Rate | Inventory optimization, supply-demand balancing |
| Final Integration | Product Pass Rate, Integration Time, Rework % | Allocation models, backlog analysis |
| Distribution & Fulfillment | OTIF, Inventory Turns, Backlog | Network optimization, customer service improvement |

Key Supply Chain & Analytics Applications wrt MP

- Inventory Optimization – Sync flash supply with controller availability.
- Cycle Time Analysis – Predict delays and downtime.
- Yield Forecasting – Link process variables to defect trends.
- Capacity Planning – Optimize machine scheduling and labor shifts.
- Supplier Monitoring & Line Balancing – Scrap/root cause analysis for rejections.

3.San Disk Products

| Category | Product Types | Use Case / Segment |
|---------------------------|--|---------------------------------------|
| Consumer Storage | USB flash drives, SD/microSD cards, portable SSDs | Cameras, smartphones, file transfers |
| Solid State Drives (SSDs) | Internal SSDs (SATA, NVMe), External SSDs | Laptops, desktops, creative workflows |
| Mobile Storage | iXpand flash drives (iPhone), dual USB-C drives | Mobile backup, cross-device transfer |
| Gaming Storage | WD_BLACK SN series, SanDisk microSD for Nintendo Switch | Console and PC gaming |
| Professional Storage | SanDisk Professional (G-Drive, G-Raid, G-Speed) | Photography, videography, media |
| Embedded Flash | eMMC, iNAND, UFS chips | Smartphones, tablets, automotive |
| Memory Cards | Extreme PRO SD/microSD, Ultra series | Photography, drone, surveillance |
| Cloud & Data Center Flash | U.2, U.3, E1.S enterprise SSDs, OpenFlex NVMe-oF platforms | Data centers, cloud infrastructure |

Upcoming Products 2025 Road map

| | |
|-------------------------|--|
| BiCS6 & BiCS8 NAND | 218-layer and beyond 3D NAND flash developed in JV with Kioxia (higher density, faster speeds) |
| PCIe Gen 5 NVMe SSDs | For high-performance computing, gaming, and enterprise use |
| AI + Edge Storage | New SSDs and flash solutions optimized for edge computing and AI workloads |
| Sustainability in Flash | Eco-friendly packaging, energy-efficient drives, longer lifecycle support |
| i-NAND Smart SLC | Advanced NAND for automotive and industrial IoT markets |
| Automated Supply Chain | Integration of AI/ML tools for planning, inventory, and factory forecasting |

Core Planning Methods

| Methodology | Use Case | Tools |
|--|---|---------------------------------|
| Forecasting (Time Series, ML) | Demand prediction, material consumption | Python, Power BI,ARIMA,LSTM |
| Optimization (Linear, Integer) | Capacity planning, production scheduling | Gurobi, FICO, Excel Solver |
| Simulation | What-if analysis on fab/assembly delays | Python, Arena (if applicable) |
| Inventory Analysis (EOQ, Safety Stock) | Stock level balancing across global locations | Excel, SQL |
| Data Visualization | KPI dashboards for executive and operations teams | Power BI, Tableau |
| Root Cause Analysis | Identifying delay, quality, or yield issues | Python, 5-Why, Fishbone Diagram |

4. SanDisk Flash Business Landscape /Market Trends– 2025

1. Market Downturn & Production Cuts

- NAND market faces oversupply and weak demand (smartphones, laptops, SSDs).
- SanDisk, Micron, Samsung, SK hynix cutting production via lower fab utilization.
- Chinese competitors expanding rapidly.
- Long-term: Industry moving toward consolidation and innovation-driven survival.

2. SanDisk Price Increase – April 2025

- >10% NAND price hike planned from April 1, 2025.
- Driven by:
 - Expected supply-demand recovery in H2 2025.
 - Rising tariffs and cost pressure.
- SanDisk is positioning early for market rebound.

3. Spin-Off & High-Bandwidth Flash (HBF) Innovation

- SanDisk separated from Western Digital in Feb 2025; continues JV with Kioxia.
- Focused on 112/162-layer BiCS NAND vs. competitors' 218-layer.
- Developing High-Bandwidth Flash (HBF) as a next-gen NAND alternative to HBM.
 - 8–16x capacity of HBM at similar cost.
 - Could redefine supply chain architecture for advanced memory systems.

Fab Locations

| Location | Function |
|------------------------|---------------------------------------|
| Yokkaichi (Japan) | NAND wafer fabrication (Kioxia+WD JV) |
| Asia (Malaysia, China) | Assembly, testing, packaging |
| Milpitas (USA) | Global planning, R&D, logistics, SCM |
| Customer regions | Distribution and final delivery |

SD-locations worldwide

| Region | Site Name | Role | Ownership |
|----------|----------------------|----------------------------------|------------------------|
| Japan | Yokkaichi (Fabs 1–7) | Wafer fabrication (NAND) | JV w/ Kioxia |
| Japan | Kitakami | Expansion fab site (3D NAND) | Kioxia-led, WD-partner |
| Malaysia | Penang | Assembly, packaging, and testing | WD-owned |
| China | Shanghai, Shenzhen | ATP + Logistics | WD-owned |
| USA (CA) | Milpitas | HQ, Supply Chain Planning, R&D | WD-owned |
| India | Bangalore | R&D, Engineering | WD-owned |

Tools currently used in SD for SC Demand forecasting

| Category | Tools / Models Used |
|--------------------------------------|--|
| Forecasting Models | ARIMA, SARIMA, SARIMAX, Facebook Prophet, NeuralProphet |
| Machine Learning Models | XGBoost, LightGBM, Random Forest, Gradient Boosted Trees |
| Deep Learning Models | RNN, LSTM, GRU, Temporal Fusion Transformer (TFT) |
| AI/ML Platforms | SAP IBP, Blue Yonder (JDA), Kinaxis RapidResponse, Anaplan |
| Data Processing | Python (Pandas, NumPy), Spark, Kafka, SQL |
| Visualization & Reporting | Power BI, Tableau, Excel, Explainable AI Dashboards |
| Model Evaluation Metrics | MAPE, RMSE, MAE, Forecast Value Add (FVA), Service Level Impact, Inventory Turns |
| Real-time Forecasting Tools | Demand Sensing Engines, Streaming Analytics, Real-time POS/Market Data Integration |
| Simulation & Optimization | What-if Scenario Simulations, Gurobi, Linear Programming |
| AI Assistants & GenAI | Generative AI Copilots, LLM-based Forecast Summary Tools |

SC Keywords for project reference

| Term | Meaning |
|--------------------------------|---|
| Lead Time | Total time from order placement to delivery. |
| Cycle Time | Time taken to complete one unit of production. |
| Throughput | Number of units produced or moved through a system in a given time. |
| Inventory Turnover | How often inventory is sold and replaced over a period. |
| Stockout | When demand cannot be met due to no inventory. |
| Safety Stock | Extra inventory kept to prevent stockouts. |
| Order Quantity (EOQ) | Optimal amount to order to minimize cost. |
| Bullwhip Effect | Demand fluctuations amplified upstream in the supply chain. |
| Just-In-Time (JIT) | Inventory system aimed at reducing waste by receiving goods only as needed. |
| Kanban | Visual scheduling system to manage workflow and inventory. |
| Capacity Planning | Ensuring production can meet current and future demand. |
| Demand Forecasting | Predicting future customer demand using historical data. |
| Supply Chain Visibility | Ability to track products/components across the supply chain in real time. |
| Logistics | Coordination of moving goods, services, and information. |
| Warehouse Management | Efficient handling and storage of goods within a warehouse. |

My Project Proposal (driven by above inputs)

“Next-Gen GSCP Framework: AI-Powered Demand-Lead Synchronization & Unified Planning Model for SanDisk’s High-Bandwidth Flash Supply Chain”

Problem Context – Real-World Challenges at SanDisk HQ (Milpitas, 2025)

As of Q2 2025, SanDisk is navigating a **fragile recovery** in the NAND flash market. The **Milpitas HQ**, being the central node for global supply planning, is experiencing severe pressure due to:

- **Volatile consumer demand** (smartphones, SSDs, AI servers) → inaccurate forecasts
- **Overcapacity → reduced fab utilization** → underutilized assets
- **Pricing shifts** → SanDisk has announced a >10% NAND price hike (April 2025)
- **Transition to High-Bandwidth Flash (HBF)** → newer SKUs, complex BOMs, and supply bottlenecks – No product historic data
- **Disruption in ocean freight and silicon availability**
- **Split from Western Digital** → reconfiguration of planning systems, data integration, and team workflows

Current planning tools (Excel + i2 (Blue Yonder) /SAP + dashboards) lack:

- Real-time AI inference
- Predictive risk classification
- Connected visibility between demand, inventory, fab/test capacity, and logistics

This project proposes a next-gen AI-powered GSCP model — grounded in **SC 5.0** — to address these issues head-on.

A **Unified Demand Model** is a comprehensive framework that consolidates all forms of demand signals across the supply chain — from customers, channels, markets, and internal sources — into a **single, coherent model** that supports **end-to-end planning and synchronization** - supports **S&OP, MPS, MRP, and ATP** in a consistent way.

Project Goal:

To build a **prototype of Next Gen GSCP framework system** using advanced analytics, ML, and optimization to solve real-world planning inefficiencies across SanDisk's Milpitas operations, specifically tuned to 2025's flash business landscape.

Core Modules (Current vs. Future (with Tech References))

1. Demand Forecasting + Market Signal Integration

- **Current State at Milpitas:** Time-series based planning using SAP i2 & Excel; limited external signal input.
- **Proposed Upgrade:**
 - ML Models: Prophet, LSTM, XGBoost (Amazon Forecast, Google Vertex AI)
 - External signal fusion: import electronics market indices, tariffs, AI server shipment forecasts
 - Rolling horizon forecast with **auto-tuning based on MAPE**
 - **SAP IBP Copilot (SAP Joule)** to analyze transactional deltas + suggest forecast overrides

- Inspired by Amazon's Sage Maker + Adidas case study; Google's Wayfair deployment (Vertex AI pipelines).

2. Unified Data Model (UDM) & Master Data Layer

- **Current State:** Siloed BOMs, planning inputs, lead times; manual extraction from SAP tables
- **Proposed Upgrade:**
 - UDM built on Python + SQL layer mimicking SAP's digital core
 - Sync BOM, routing, lead times, production cycles into a real-time model
 - Foundation for optimization engines to "see" true constraints

-Inspired by SAP Digital Core, Siemens Xcelerator architecture, and IBM Sterling's master data governance.

3. Capacity + Inventory Optimization (Pyomo + Gurobi)

- **Current State:** Capacity planning manually driven through i2 & Excel simulations

- **Proposed Upgrade:**

- MILP models to dynamically optimize lot sizes, wafer allocation, and test scheduling
- Integrates constraints like fab downtime, forecasted demand, and holding/backorder costs

-NVIDIA uses similar AI planning for silicon wafer alignment across their fabs.

4. Shortage & Supplier Risk Prediction (ML Classifier)

- **Current State:** Shortage risk is reactionary — flagged only after issue

- **Proposed Upgrade:**

- Random Forest + XGBoost models to classify parts with single sourcing + long lead time
- Input BOM exploded at component level → alert for at-risk SKUs
- Automate weekly exception dashboards via Power BI

-Intel's predictive risk analytics and Lenovo's IBM-powered visibility inspired this.

5. Logistics Network Optimization Using AI

- **Current State:** Static routing via TMS; no proactive exception detection

- **Proposed Upgrade:**

- Use **AI-based network design** (AWS/Amazon's last-mile and OTD strategy) to optimize:
 - Ocean vs. air freight prioritization
 - Supplier consolidation routes
 - Predictive lead time classification
- KPI focus: OTIF (On Time In Full), backlog %, delivery window adherence

-DHL's AI-driven robotics + IBM's scope 3 emissions reduction via TMS data used as blueprints.

Key Supply Chain 5.0 Features Incorporated (with Real-World Inspiration)

| SC 5.0 Feature | Real-World Implementation |
|----------------------------|--|
| Human-AI Collaboration | SAP Joule Copilot – AI-generated insights for planners |
| Sustainability & Emissions | IBM + DHL – Scope 3 emissions using TMS + smart transport |
| Unified Decision Models | Siemens + SAP – Xcelerator + Control Tower UDM |
| Cognitive Automation | Deloitte Cognitive SC – AI assistants for predictive planning |
| Digital Twins | NVIDIA Omniverse – Real-time fab simulation and capacity bottleneck prediction |
| Pattern-Based Forecasting | Amazon Forecast – External market signal injection |
| ERP-to-AI Integration | SAP IBP + Vertex AI – linking transactional data with optimization engines |

Expected Results by August 2025 (Q2 End):

| Challenge | Solved By | Outcome |
|---|---|---|
| Inaccurate NAND/HBF demand plans | ML-based forecast + SAP Joule overrides | ↑ Fill Rate, ↓ Inventory obsolescence |
| Fab/test bottlenecks & underutilization | MILP optimization | ↑ Capacity Utilization, ↓ Backorders |
| SKU-level shortages | ML-based risk classification | Proactive alerts → ↓ Expedited costs |
| Ocean freight/logistics risk | AI-driven routing | ↑ OTIF, ↓ Transit cost variance |
| Manual reporting inefficiencies | Power BI + SAP CoPilot | ↓ Planner effort by 40% |
| Strategic agility vs. Samsung | Pattern-driven forecasts + sustainability KPI | Competitive edge in cost + carbon footprint |

Industry 4.0 vs 5.0 at Japan Plants: Current & Proposed Digital Foundation

Current State (Industry 4.0)

- MES + SAP i2 used
- Basic sensor data + fab control systems
- No live digital twin or AI-enabled decision support

Proposed Shift (Industry 5.0)

- Use Digital Twin (via Python or NVIDIA Omniverse model)
 - Simulate fab output vs. forecast error → real-time feedback
 - Integrate fab downtimes into optimization models
- SAP IBP Copilot layer for Gen AI planning
- Real-time inventory tracking via ML models + IOT feed

Recommended Tools & Technologies for Next-Gen GSCP at SanDisk

| Category | Purpose & Use Case | Tools / Models Used |
|-------------------------|--|--|
| Forecasting Models | Handle volatility in NAND/HBF demand across global markets | - Facebook Prophet, Neural Prophet (quick deployment) - ARIMA, SARIMA, SARIMAX (short-term forecast tuning) - Temporal Fusion Transformer (TFT) – time series with attention for HBF ramp-up |
| Machine Learning Models | Shortage risk classification, lead time prediction, demand-supply mismatch detection | - XG Boost, Light GBM, Random Forest (fast + interpretable) - Gradient Boosted Trees for feature interaction modeling |
| Deep Learning Models | Detect hidden patterns in demand + capacity fluctuations | - LSTM, GRU, RNN – long-sequence memory - Transformer-based models for multi-variate time series |
| AI/ML Platforms | End-to-end AI-powered planning platforms for real-time planning | - SAP IBP + SAP Joule Copilot (existing at SanDisk) - Kinaxis Rapid Response (event-based, demand-supply alignment) - Blue Yonder (JDA) (used by Western Digital before split) - Anaplan (scenario modeling for exec-level S&OP) |

| Category | Purpose & Use Case | Tools / Models Used |
|---|--|--|
| Digital Twin + Simulation | Simulate fab/test output and bottlenecks, model impact of Kioxia capacity shifts | - NVIDIA Omniverse (visual + ML-enabled twins) - Any Logic (discrete + agent-based SCM sim) - Flex Sim / Promodel (plant-level what-if analysis) |
| Supply Chain Optimization | Optimize lot sizing, fab utilization, test/burn-in balancing | - Gurobi, CPLEX, Pyomo (MILP/LP for inventory-capacity balancing) - What-if Scenario Planners (SAP IBP, Anaplan embedded) |
| Real-time Forecasting / Demand Sensing | Ingest POS, eComm, ODM order signals for short-term planning | - Streaming analytics via Kafka, Spark Structured Streaming - Demand sensing engines from Kinaxis / SAP - AWS Forecast or Google Cloud Vertex AI pipelines |
| Data Processing + ETL | Clean, enrich, and merge master data from SAP, Kioxia feeds, and planning teams | - Python (Pandas, NumPy) - SQL (Oracle, SAP HANA) - Apache Spark, Airflow for scheduling - Data Lake connectors (AWS Glue, GCP DataPrep) |
| Visualization & Reporting | Planner-facing dashboards, shortage alerts, capacity trend views | - Power BI (used by SanDisk) - Tableau (for rapid dashboard builds) - Explainable AI Dashboards (SHAP, LIME) for model transparency |
| Model Evaluation Metrics | Validate models for reliability + cost impact | - MAPE, RMSE, MAE (forecast accuracy) - Forecast Value Add (FVA) – planner vs. model ROI - Service Level Impact, Inventory Turns, Fill Rate |
| AI Assistants & Gen AI | Planning copilots, summary generation, forecast commentary | - SAP Joule (GenAI Copilot for IBP) - LLM-based tools for “Why forecast changed?” - ChatGPT / Vertex AI Gen Apps (summarizing exception reports) |

How this Project Strengthens GSCP Under the Kioxia JV

| # | Challenge | Your Project's Solution | Strategic Impact |
|---|--|---|--|
| 1 | Limited fab data visibility | Build a digital twin using inferred fab metrics (cycle times, yield, downtime) | Simulate and anticipate fab-side delays; better planning accuracy |
| 2 | Inaccurate forecast commitments – due to internal MP changes | Use ML models (Prophet, LSTM, XGBoost) with internal + external signals | Improves demand commit accuracy; reduces over/under allocation from JV |
| 3 | No proactive shortage alerts | Develop risk classification model for at-risk SKUs (lead time, BOM, sourcing) | Enables early mitigation and alternate sourcing |
| 4 | Capacity mismatch risk | Optimize production with MILP (Gurobi, Pyomo) considering fab constraints | Balances wafer supply vs. demand and reduces scrap/backorders |
| 5 | Disconnected planning collaboration | Automate insights with Power BI + SAP Joule copilots | Real-time visibility, faster decisions, fewer manual errors |
| 6 | Competitor edge (e.g., Samsung's vertical integration) | Integrate AI + digital tools to match or exceed SC responsiveness | Builds a smarter, agile GSCP despite shared manufacturing model |

SanDisk Supply Chain: Upstream vs. Downstream

| Flow | Example Companies / Partners | Push / Pull System | Where this Project Helps |
|--|--|---|--|
| Upstream (Suppliers) | - Kioxia (JV fab partner)- ASE (assembly & test)- Tokyo Electron (fab equipment)- Wafer/material vendors (e.g., SUMCO, Shin-Etsu) | Push System (SanDisk forecasts → suppliers push inventory) | - Predict fab lead times using ML- Simulate wafer delays via digital twin- Classify BOM parts with supplier risk- Optimize upstream buffer levels using MILP |
| Downstream (Customers & Distribution) | - OEMs (e.g., Dell, Lenovo)- Retailers (e.g., Best Buy, Amazon)- Channel distributors (e.g., Ingram Micro)- eCommerce (WD/SanDisk.com) | Pull System (Customer demand pulls inventory from DCs/factories) | - Forecast demand using LSTM/XGBoost models- Allocate supply based on market/channel trends- Visualize stockouts & OTIF risk in Power BI |

Push vs. Pull in SanDisk's Next-Gen Product Strategy (HBF, BiCS NAND)

| Stage | Push or Pull? | Role of ATO & MRP | My Project's Strategy |
|---|-------------------|---|---|
| Wafer Fabrication (Kioxia JV) | Push | Based on forecasted wafer demand , SanDisk places fab orders in advance using long-term capacity planning. MRP schedules wafer input based on future assembly needs. | - ML-based demand forecasting (Prophet, LSTM)- Simulate fab constraints with digital twin - MILP to optimize fab output by layer node (e.g., 112L, 162L)- Risk classification for wafer supply shortage |
| Component Procurement (Controllers, Substrates) | Push | Purchased in anticipation of final assembly needs. MRP explodes demand from planned finished goods. | - Use BOM explosion to forecast sub-component needs- Classify risky parts (e.g., single-source) using ML- Optimize buffer inventory based on shortage risk |
| Assembly & Packaging | Pull (ATO) | SanDisk operates on an Assemble-to-Order basis: products are assembled after customer demand is known, based on pre-positioned wafers and components. MRP ensures sub-assemblies are staged ahead of time. | - Align MRP with ML forecasts for better staging- Visualize real-time inventory vs. demand match in Power BI- Forecast SKU-level demand using market signals- Gen AI to suggest schedule overrides |
| Order Fulfillment & Logistics | Pull | Orders are fulfilled post-assembly based on demand from OEMs or retail. Planning here is demand-driven and sensitive to delivery performance (OTIF). | - Predict OTIF risk and logistics delays using AI- Route optimization (logistics network AI)- KPI dashboards to track customer service metrics |

Bullwhip Effect at SanDisk – Summary & Project Mitigation

| Aspect | Explanation |
|------------------------------|--|
| What is the Bullwhip Effect? | A supply chain phenomenon where small changes in customer demand cause increasingly larger demand fluctuations upstream (e.g., fab, suppliers), leading to inefficiencies. |

SanDisk-Specific Bullwhip Scenarios & Project Solutions

| Supply Chain Layer | Bullwhip Scenario at SanDisk | My Project’s Solution |
|------------------------|--|--|
| Retail / OEM Demand | Sudden spike in SSD demand (e.g., AI laptops) leads to aggressive OEM ordering | ML forecasting (LSTM, XGBoost) reduces forecast error and overreaction |
| Assembly & Packaging | Excess build orders for BiCS NAND or controllers based on outdated demand | Unified Data Model aligns real-time demand with component planning |
| Wafer Fab (Kioxia JV) | Overordering wafers for older node (e.g., 112L) while demand shifts to 162L | Digital twin simulates fab output + MILP optimizes wafer allocation |
| Raw Material Suppliers | Excess raw material orders from perceived shortages upstream | Supplier risk model + lead time prediction avoids panic ordering |

Overall Project Impact

| Result | Benefit to SanDisk GSCP |
|------------------------|--|
| ↓ Demand Amplification | More stable ordering across supply chain tiers |
| ↓ Inventory Costs | Avoids overstock and obsolete inventory |
| ↑ Service Levels | Better product availability for customers |
| ↑ Planning Accuracy | Less rework, smoother fab-to-assembly flow |

SanDisk Supply Chain Planning Intern – 2025 Action Plan Summary

| Objective | Action | Value to SanDisk | Trends Impacting This Area |
|--|---|--|---|
| 1. Analyze Supply Chain Data | Extract and analyze demand, inventory, and production data for flash memory | Identify inefficiencies and improve visibility during volatile market shifts | Shift from overproduction to lean planning due to global NAND oversupply and tariff pressures |
| 2. Improve Demand Forecasting | Build or support forecasting models using time series or ML | Enhance forecast accuracy to align production with real-world demand | Recovery in NAND pricing , volatile consumer electronics demand , AI workload growth |
| 3. Optimize Inventory & Capacity | Use LP/IP models to suggest optimal fab utilization and inventory levels | Balance cost, capacity, and revenue across BiCS node layers | Production focus shifting to 112/162-layer optimization , fab cuts, and price stabilization goals |
| 4. Automate & Visualize Processes | Build KPI dashboards, automate reporting workflows | Enable real-time decision-making and reduce manual effort | Increased need for agile dashboards and data-driven ops in response to industry volatility |
| 5. Support Strategic Projects | Research competitor trends, contribute to planning for HBF adoption and fab node strategies | Provide actionable insights to strengthen SanDisk's competitive edge | Rise of High-Bandwidth Flash (HBF) , pressure to innovate against 218+ layer competition |

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
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- **LLMs – 4.0 model to give final formatted data.**

| Concept | Definition & Use | Formulas / Methods | Key Variables | Application to SanDisk SCP Intern Role |
|--------------------------------------|---|---|--|--|
| Demand Forecasting | Estimating future product demand based on historical data and trends. | <ul style="list-style-type: none"> - Moving Average: $F = \frac{D_1 + D_2 + \dots + D_n}{n}$ - Exponential Smoothing: $F_t = \alpha D_{t-1} + (1 - \alpha) F_{t-1}$ - Linear Regression: $Y = a + bX$ | D : Demand F : Forecast α : Smoothing constant | Improve forecast accuracy for Flash memory demand using Python, Excel, or ML models to optimize production and avoid over/understocking. |
| Aggregate Planning (APP) | Medium-term (6–18 months) balancing production rate, inventory, and workforce levels. | Chase, Level, Hybrid strategies | N/A | Align capacity and inventory at SanDisk's fabs in Milpitas based on market forecasts and global supply trends. |
| Master Production Scheduling (MPS) | Weekly schedule to produce finished goods as per forecast and demand. | Outputs: Weekly planned production | <ul style="list-style-type: none"> - MPS - Forecast - Inventory levels | Supports translating demand forecasts into weekly fab production plans for NAND wafers or SSDs. |
| Material Requirements Planning (MRP) | Determines raw material and component needs based on BOM and lead time. | Inputs: MPS, BOM Output: Planned order schedule | <ul style="list-style-type: none"> - Lead Time - Inventory status - BOM | Helps ensure timely supply of critical components for Flash memory manufacturing. |

| | | | | |
|--------------------------------------|---|--|---|---|
| | levels. | | | global supply trends. |
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| Lot Sizing / EOQ | Decides how much to order to minimize inventory cost. | EOQ: $\sqrt{\frac{2DS}{H}}$ Total Cost: $DC + \frac{D}{Q}S + \frac{Q}{2}H$ | D : Demand S : Setup/order cost H : Holding cost Q : Order qty | Minimize holding/ordering cost of inventory at SanDisk's supply chain nodes (e.g., fabs or logistics hubs). |
| Reorder Point (ROP) | Inventory level at which to reorder to avoid stockouts. | ROP: $d \times L$ | d : Daily demand L : Lead time | Set smart reorder thresholds for critical raw materials in volatile demand scenarios. |
| Total Inventory Cost | Sum of all inventory-related costs. | $TC = DC + \frac{D}{Q}S + \frac{Q}{2}H$ | Same as EOQ variables | Supports evaluating cost impact of inventory strategies, helping to optimize warehouse use. |
| Capacity Planning | Ensures sufficient resources (labor/machines/time) to meet demand. | Utilization = $\frac{\text{Actual Output}}{\text{Capacity}} \times 100\%$ | Output, Capacity, Time | Help adjust capacity planning models during production slowdowns or demand surges. |
| ABC Analysis | Prioritizes items in inventory based on usage value. | A = High control B = Med  C = Low | Item cost & consumption | Identify high-value NAND components or SKUs requiring tighter |

ISE 230 Concepts with Formulas & SanDisk Application

| Topic | Key Concept & Formula | Variables | Application to SanDisk GSCP |
|-------------------------|--|---|---|
| Linear Programming (LP) | Maximize or Minimize: $Z = c_1x_1 + c_2x_2 + \dots + c_nx_n$ Subject to: $a_{11}x_1 + a_{12}x_2 + \dots \leq b_1$ $x_i \geq 0$ | Z : Objective (e.g., cost, profit) x_i : Decision variables c_i : Coefficients a_{ij} : Constraint coefficients b_i : RHS | Optimize production plans across multiple fabs and products to minimize cost or maximize throughput. |
| Sensitivity Analysis | Shadow Price: Change in Z per unit increase in RHS. Allowable range = stable zone for objective coefficients. | RHS: Right-hand side of constraint Shadow price: Dual value | Helps understand how much capacity or demand can vary before your supply chain plan becomes suboptimal. |
| Transportation Problem | Minimize: $\sum_{i=1}^m \sum_{j=1}^n c_{ij}x_{ij}$ Subject to: $\sum_j x_{ij} = a_i$, supply $\sum_i x_{ij} = b_j$, demand | c_{ij} : Cost from source i to destination j x_{ij} : Units shipped a_i, b_j : Supply & demand | Optimize shipping of NAND wafers from fabs to global DCs to reduce cost & lead time. |
| Integer Programming | Same as LP, but with $x_i \in \mathbb{Z}$ or $x_i \in \{0, 1\}$ | Binary: 0/1 (Yes/No) decisions | Solve supplier selection problems or production facility location decisions where partial assignments aren't allowed. |



| | | | |
|--------------------------|---|--|---|
| Markov Chains | Transition Matrix: P Steady state: $\pi P = \pi$, with $\sum \pi_i = 1$ | π : Steady-state probabilities P : Transition probabilities | Model product lifecycle transitions (e.g., Intro → Growth → Maturity) or machine reliability in fabs. |
| Queuing Theory (M/M/1) | Utilization: $\rho = \frac{\lambda}{\mu}$ Avg # in system: $L = \frac{\lambda}{\mu - \lambda}$ Avg wait time: $W = \frac{1}{\mu - \lambda}$ | λ : Arrival rate μ : Service rate ρ : Utilization | Model wafer test station usage to avoid bottlenecks and reduce fab cycle time. |
| Poisson Distribution | $P(X = k) = \frac{(\lambda t)^k e^{-\lambda t}}{k!}$ | λ : Event rate t : Time window k : # of events | Model arrival of customer orders, breakdowns, or late shipments. |
| Project Management (CPM) | Critical Path = longest duration path in the network Slack = Latest Start - Earliest Start | Activities, durations, dependencies | Optimize global product launch plans (e.g., BiCS layer transitions or SSD ramp-ups). |

